

2920SMD Series

Features

- Surface Mount Devices
- Lead free device
- Size 7555mm/2920 mils
- Surface Mount packaging for automated assembly
- Agency recognition:

Applications

- Almost anywhere there is a low voltage power supply, up to 60V and a load to be protected, including:
- Computer mother board, Modem.
 - Telecommunication equipments.

Performance Specification

Model	V _{max} (Vdc)	I _{max} (A)	I _{hold} @25°C (A)	I _{trip} @25°C (A)	P _d Max. (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	R _{i_min} (Ω)	R _{1_max} (Ω)
2920SMD030L	60	10	0.30	0.60	1.5	1.5	3.0	0.600	4.800
2920SMD050L	60	10	0.50	1.00	1.5	2.5	4.0	0.180	1.400
2920SMD075L	33	40	0.75	1.50	1.5	8.0	0.3	0.100	1.000
2920SMD100L	33	40	1.10	2.20	1.5	8.0	0.5	0.065	0.410
2920SMD125L	33	40	1.25	2.50	1.5	8.0	2.0	0.050	0.250
2920SMD150L	33	40	1.50	3.00	1.5	8.0	2.0	0.035	0.230
2920SMD185L	33	40	1.85	3.70	1.5	8.0	2.5	0.030	0.150
2920SMD200L	16	40	2.00	4.00	1.5	8.0	4.5	0.020	0.120
2920SMD250L	16	40	2.50	5.00	1.5	8.0	16.0	0.020	0.085
2920SMD260L	6	40	2.60	5.20	1.5	8.0	10.0	0.014	0.075
2920SMD300L	16	40	3.00	6.00	1.5	8.0	20.0	0.012	0.048

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.

I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.

V_{max} = Maximum operating voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

P_d = Maximum power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

R_{imin/max} = Minimum/Maximum device resistance prior to tripping at 25°C.

R_{1_max} = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to 85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		



I_{hold} versus temperature

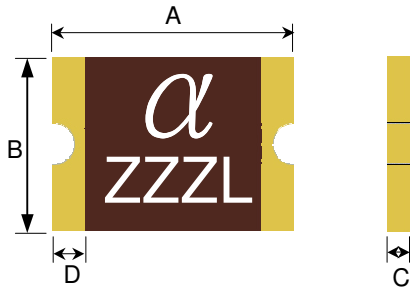
Model	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
2920SMD030L	0.45	0.40	0.35	0.30	0.25	0.23	0.20	0.17	0.14
2920SMD050L	0.76	0.67	0.59	0.50	0.42	0.38	0.33	0.29	0.23
2920SMD075L	1.13	1.01	0.88	0.75	0.62	0.56	0.50	0.44	0.34
2920SMD100L	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
2920SMD125L	1.89	1.68	1.46	1.25	1.04	0.94	0.83	0.73	0.56
2920SMD150L	2.27	2.01	1.76	1.50	1.25	1.13	1.00	0.87	0.74
2920SMD185L	2.80	2.47	2.17	1.85	1.54	1.39	1.22	1.07	0.85
2920SMD200L	3.02	2.68	2.34	2.00	1.66	1.50	1.32	1.16	0.90
2920SMD250L	3.78	3.35	2.93	2.50	2.08	1.88	1.65	1.45	1.13
2920SMD260L	3.64	3.25	2.91	2.60	2.26	2.08	1.95	1.74	1.13
2920SMD300L	4.53	4.02	3.51	3.00	2.52	2.26	1.99	1.75	1.34

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Construction and Dimension (Unit:mm)

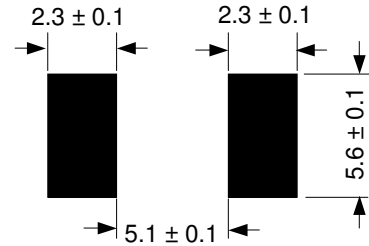
Model	A		B		C		D
	Min.	Max.	Min.	Max.	Min.	Max.	Min.
2920SMD030L	6.73	7.98	4.80	5.44	0.60	1.15	0.30
2920SMD050L	6.73	7.98	4.80	5.44	0.60	1.15	0.30
2920SMD075L	6.73	7.98	4.80	5.44	0.60	1.15	0.30
2920SMD100L	6.73	7.98	4.80	5.44	0.40	1.00	0.30
2920SMD125L	6.73	7.98	4.80	5.44	0.40	0.90	0.30
2920SMD150L	6.73	7.98	4.80	5.44	0.40	0.90	0.30
2920SMD185L	6.73	7.98	4.80	5.44	0.30	0.90	0.30
2920SMD200L	6.73	7.98	4.80	5.44	0.30	0.90	0.30
2920SMD250L	6.73	7.98	4.80	5.44	0.30	0.90	0.30
2920SMD260L	6.73	7.98	4.80	5.44	0.30	0.90	0.30
2920SMD300L	6.73	7.98	4.80	5.44	0.30	0.90	0.30

Dimensions & Marking



α = Trademark
ZZZ = Hold current

Recommended pad layout (mm)



Termination pad characteristics

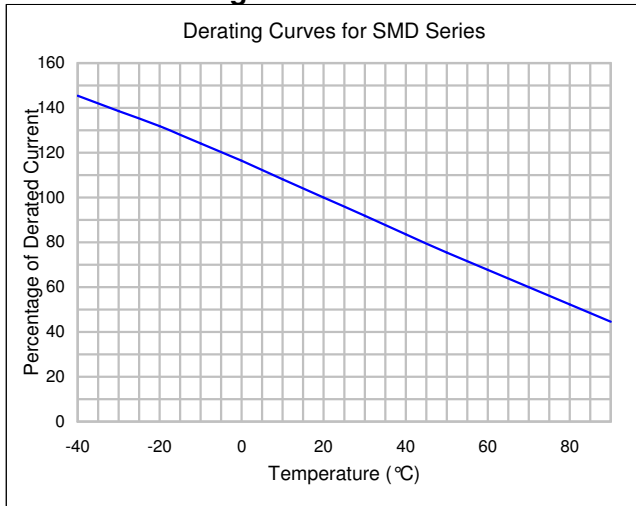
Terminal pad materials : Tin-Plated Nickle-Copper or Gold-Plated Nickle-Copper

Terminal pad solderability : Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

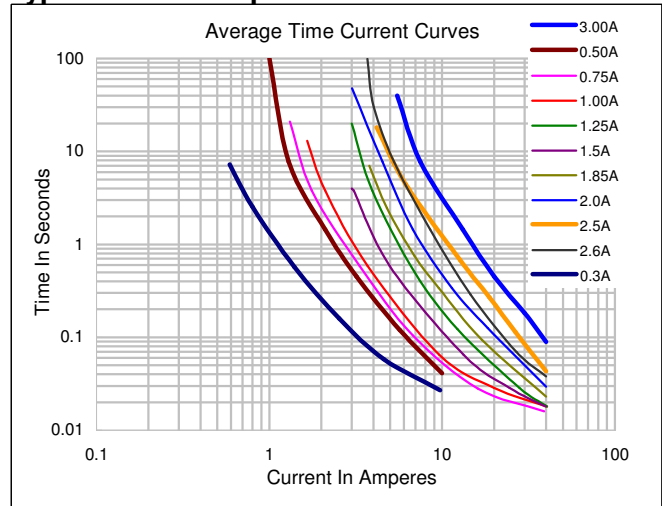
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal derating curve

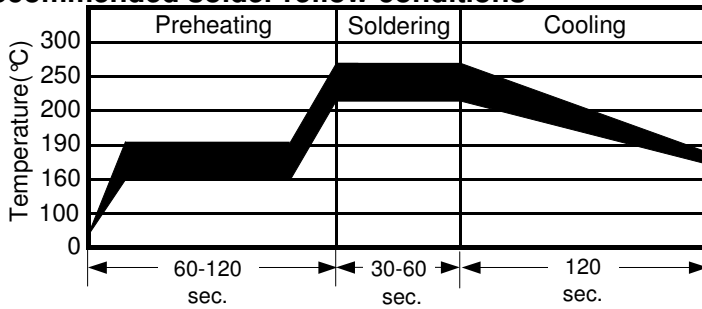


Typical time-to-trip at 25°C



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Recommended solder reflow conditions

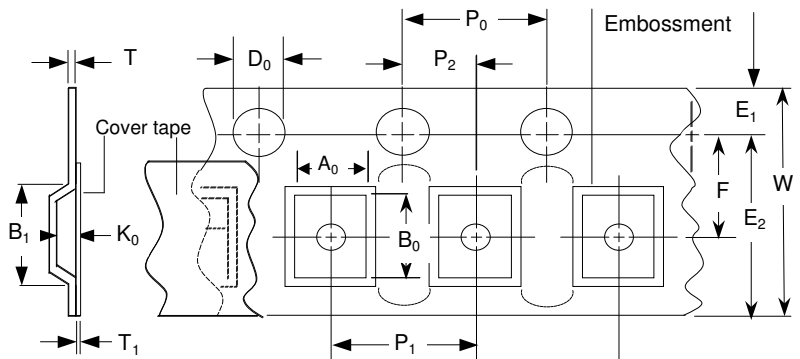


- Recommended reflow methods : IR, vapor phase oven, hot air oven.
 - Devices are not designed to be wave soldered to the bottom side of the board.
 - Recommended maximum paste thickness is 0.25 mm (0.010 inch).
 - Devices can be cleaned using standard method and solvents.
- Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

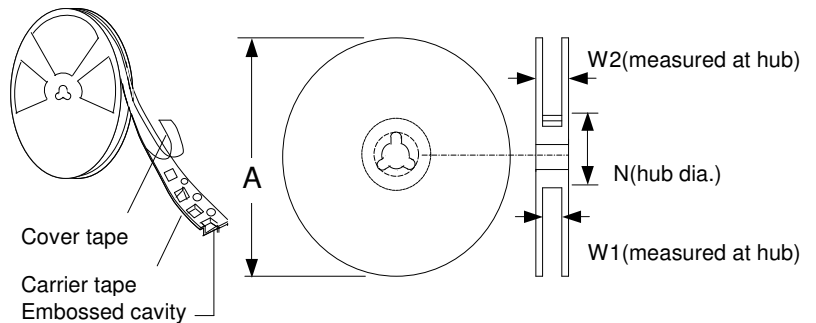
Tape and reel specifications (mm)

SMD	
Governing Specifications	EIA 481-2
W	16.0 ± 0.3
P ₀	4.0 ± 0.10
P ₁	8.0 ± 0.10
P ₂	2.0 ± 0.05
A ₀	5.70 ± 0.10
B ₀	8.00 ± 0.10
B ₁ max.	12.1
D ₀	1.5 + 0.1, -0
F	7.5 ± 0.05
E ₁	1.75 ± 0.10
E ₂ min.	14.25
Tmax.	0.6
T ₁ max.	0.1
K ₀	0.80 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	60
W ₁	16.4 + 2.0, -0.0
W ₂ max.	22.4

EIA Tape Component Dimensions



EIA Reel Dimensions



Storage and handling

- Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

Order information

Packaging

2920SMD	050L	Tape & Reel Quantity
Product name	Hold	2,000 pcs/reel
size 2920 mils	Current	
SMD : surface mount device	0.50A	

Tape & reel packaging per EIA481-1